

HAT2105R

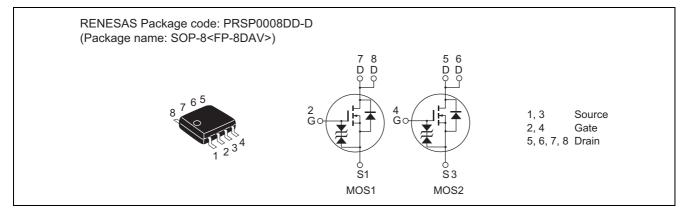
Silicon N Channel Power MOS FET High Speed Power Switching

> REJ03G1369-0100 Rev.1.00 Apr 04, 2006

Features

- Low on-resistance
- Capable of 4 V gate drive
- High density mounting

Outline



Absolute Maximum Ratings

			$(Ta = 25^{\circ}C)$
Item	Symbol	Ratings	Unit
Drain to source voltage	V _{DSS}	200	V
Gate to source voltage	V _{GSS}	±15	V
Drain current	I _D	0.5	A
Drain peak current	Note1 I _{D(pulse)}	2	A
Body-drain diode reverse drain current	I _{DR}	0.5	A
Channel dissipation	Pch Note2	1.3	W
	Pch Note3	2	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1. PW \leq 10 $\mu s,$ duty cycle \leq 1 %

2. 1 Drive operation ; When using the glass epoxy board (FR4 40 x 40 x 1.6 mm), PW \leq 10 s

3. 2 Drive operation ; When using the glass epoxy board (FR4 40 x 40 x 1.6 mm), PW \leq 10 s



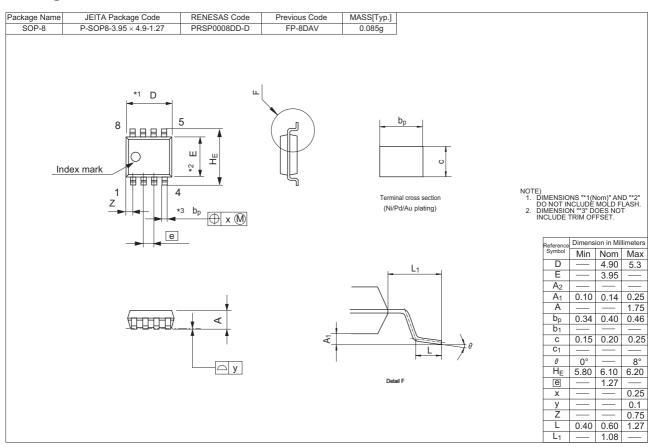
Electrical Characteristics

						$(Ta = 25^{\circ}C)$
ltem	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	V _{(BR)DSS}	200	_		V	$I_D = 10 \text{ mA}, V_{GS} = 0$
Gate to source breakdown voltage	V _{(BR)GSS}	±15	_	—	V	$I_{G} = \pm 100 \ \mu A, \ V_{DS} = 0$
Gate to source leak current	I _{GSS}	_	_	±10	μΑ	$V_{GS} = \pm 12 \text{ V}, V_{DS} = 0$
Zero gate voltage drain current	I _{DSS}	_	_	5	μΑ	$V_{DS} = 200 \text{ V}, V_{GS} = 0$
Gate to source cutoff voltage	V _{GS(off)}	1.0	_	2.1	V	V _{DS} = 10 V, I _D = 1 mA
Static drain to source on state	R _{DS(on)}	_	1.6	2.2	Ω	$I_D = 0.5 \text{ A}, V_{GS} = 10 \text{ V}^{\text{Note4}}$
resistance	R _{DS(on)}	_	1.9	2.7	Ω	$I_D = 0.5 \text{ A}, V_{GS} = 4 \text{ V}^{Note4}$
	R _{DS(on)}	_	2.4	5.5	Ω	$I_D = 2 \text{ A}, V_{GS} = 5 \text{ V}^{Note4}$
Forward transfer admittance	y _{fs}	0.56	0.86	_	S	$I_D = 0.5 \text{ A}, V_{DS} = 10 \text{ V}^{\text{Note4}}$
Input capacitance	Ciss	_	120	_	pF	V _{DS} = 10 V, V _{GS} = 0, f = 1 MHz
Output capacitance	Coss	_	29	—	pF	
Reverse transfer capacitance	Crss		10		pF	-
Turn-on delay time	t _{d(on)}	_	10	—	ns	$V_{GS} = 5 V, I_D = 0.5 A,$
Rise time	tr	_	14		ns	$V_{DD} \cong 30 \text{ V}$
Turn-off delay time	t _{d(off)}	_	24	—	ns	7
Fall time	t _f	_	9	—	ns	7
Body-drain diode forward voltage	V _{DF}		0.9	1.4	V	$I_F = 0.5 \text{ A}, V_{GS} = 0^{Note4}$

Notes: 4. Pulse test



Package Dimensions



Ordering Information

Part Name	Quantity	Shipping Container
HAT2105R-EL-E	2500 pcs	Taping

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.



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